- 1 1. A method comprising:
- 2 forming a chalcogenide access device having a
- 3 snapback voltage low enough to avoid disturbing data stored
- 4 in a memory element while reading the memory element
- 5 selected by the access device.
- 1 2. The method of claim 1 including forming the
- 2 chalcogenide access device to have a snapback voltage less
- 3 than the threshold voltage of the memory element.
- 1 3. The method of claim 2 including forming the
- 2 memory element of a phase change material.
- 1 4. The method of claim 2 including forming the
- 2 memory element of a thin film material.
- 1 5. The method of claim 1 including forming at least
- 2 two arrays of memory elements stacked one on top of the
- 3 other.
- 1 6. The method of claim 5 including forming memory
- 2 arrays with at least two memory elements each having a
- 3 chalcogenide access device.

- 1 7. The method of claim 6 including forming said
- 2 chalcogenide access devices above a semiconductor
- 3 substrate.
- 1 8. The method of claim 7 including forming said
- 2 memory elements above said semiconductor substrate.
- 1 9. The method of claim 8 including forming an access
- 2 device over a memory element.
- 1 10. The method of claim 9 including forming the
- 2 access device directly on top of the memory element without
- 3 an intervening barrier layer.
- 1 11. A memory comprising:
- a cell including a chalcogenide access device and
- 3 a memory element, the chalcogenide access device having a
- 4 snapback voltage low enough to avoid disturbing data stored
- 5 in the memory element while reading the memory element.
- 1 12. The memory of claim 11 wherein said chalcogenide
- 2 access device has a snapback voltage less than the
- 3 threshold voltage of the memory element.
- 1 13. The memory of claim 12 wherein said memory
- 2 element includes a phase change material.

- 1 14. The memory of claim 12 wherein said memory
- 2 element includes a thin film material.
- 1 15. The memory of claim 11 including at least two
- 2 memory arrays, each array including a plurality of cells
- 3 stacked one on top of the other.
- 1 16. The memory of claim 15 including at least two
- 2 memory elements each having a chalcogenide access device.
- 1 17. The memory of claim 16 including a semiconductor
- 2 substrate, said chalcogenide access devices of said two
- 3 memory elements formed above said semiconductor substrate.
- 1 18. The memory of claim 17 wherein said two memory
- 2 elements are formed above said semiconductor substrate.
- 1 19. The memory of claim 18 including an access device
- 2 located over at least one of the two memory elements.
- 1 20. The memory of claim 19 wherein the access device
- 2 is directly on top of the memory element.
- 1 21. A system comprising:
- 2 a processor-based device;

- a wireless interface coupled to said processor-
- 4 based device; and
- a memory coupled to said device, said memory
- 6 including a cell with a chalcogenide access device and a
- 7 memory element, the chalcogenide access device having a
- 8 snapback voltage low enough to avoid disturbing data stored
- 9 in the memory element while reading the memory element.
- 1 22. The system of claim 21 wherein said chalcogenide
- 2 access device has a snapback voltage less than the
- 3 threshold voltage of the memory element.
- 1 23. The system of claim 22 wherein said memory
- 2 element includes a phase change material.
- 1 24. The system of claim 21 wherein said memory
- 2 includes at least two arrays each having rows and columns,
- 3 one of said arrays stacked above the other of said arrays.
- 1 25. The system of claim 24 including two memory
- 2 elements each having a chalcogenide access device.
- 1 26. The system of claim 25 including a substrate,
- 2 said chalcogenide access devices formed above said
- 3 substrate.

- 1 27. The system of claim 26 wherein said memory
- 2 elements are formed above said semiconductor substrate.
- 1 28. The system of claim 27 including an access device
- 2 located over the memory element.
- 1 29. The system of claim 28 wherein the access device
- 2 is directly on top of the memory element.
- 1 30. The system of claim 21 wherein said access device
- 2 and said memory element include chalcogenide material and
- 3 the chalcogenide material used in the access device and the
- 4 memory element are different chalcogenide materials.
- 1 31. The system of claim 21 wherein said wireless
- 2 interface includes a dipole antenna.